



# **Electrical Specifications:**

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		100.000000		MHz	
		Fr	equency Stat	oility		
Frequency Stability	∆F/F	-25		+25	ppm	Includes calibration at +25°C plus deviation vs. temperature.
Aging		-3		+3	ppm	1 <sup>st</sup> year
			RF Output			
Output Type		Ľ	VDS Compatibl	e		
Output Load		100	Ω between out	outs		
Symmetry (duty cycle)	Vон	45		55	%	Ref. to 50% of waveform
Differential Output Voltage	VDIFF	250		450	mV	peak-to-peak differential output voltage
Rise/Fall Time	T <sub>R</sub> /T <sub>F</sub>			0.5	ns	20% to 80% of waveform
Start-up Time	Ts∪			10	ms	T <sub>ambient</sub> = +25°C
Enable Logic		70% V <sub>CC</sub> or N/C			V	Pad 1: Output Enabled
Disable Logic				30% Vcc	V	Pad 1: Output Disabled to high-Z
		Supply Volt	age & Power	Consumption	on	
Operating Voltage	Vcc	3.13	3.30	3.47	V	
Supply Current	lcc			40	mA	
		(	Other Paramete	ers		
Phase Jitter (RMS)	ΦJ			0.5	ps	12KHz to 20MHz

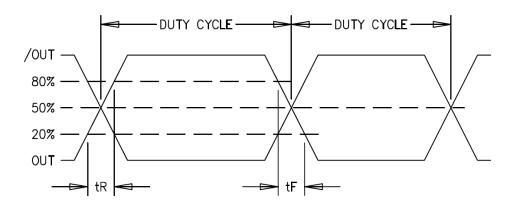
# **Environmental Requirements:**

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Operating Temperature	TA	-40		+85	С°	
Storage Temperature	Ts	-55		+125	°C	
Mechanical Shock	Per MIL-ST	D-202, Meth	od 213, Co	ndition C (100	g's, 6 ms	duration, ½ sinewave)
Vibration	Per MIL-ST	D-202, Meth	od 201 & 20	04 (10 g's from	10-2000 n	Hz)
Thermal Cycle						. dwell, 10 cycles)
Hermeticity	Per MIL-ST	D-202, Meth	od 112 (1 x	10 <sup>-8</sup> atm cc/s	of Helium)	1
Moisture Sensitivity Level (MSL)	MSL 1					
Solderability	Per EIAJ-S	FD-002				
Max. Soldering Conditions	See solder	orofile, Figur	e 1			
Package Type	2.50 mm (typ) X 3.20 mm (typ) X 1.10 (max) mm 6-pad leadless ceramic. RoHS compliant.					





## **Output Waveform:**



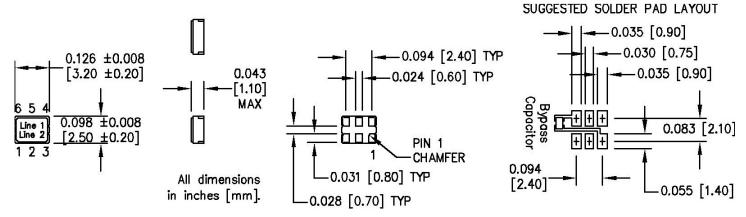
## Marking and Pin Out:

Pad	Function	
1	Enable/Disable	
2	N/C	
3	Ground	
4	Output	
5	Complementary Output	
6	+V <sub>cc</sub>	

Part Marking		
Line 1	100M0000	
Line 2	M yy ww vv	

Legend				
уу	Year			
ww	Work week			
vv	Factory code			

### **Dimensions:**

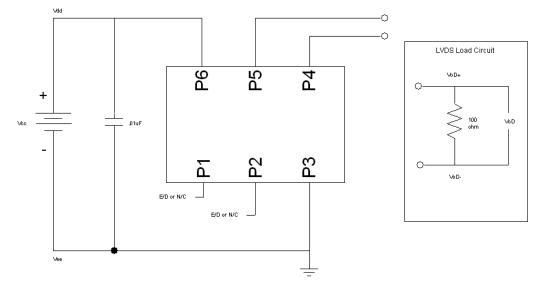


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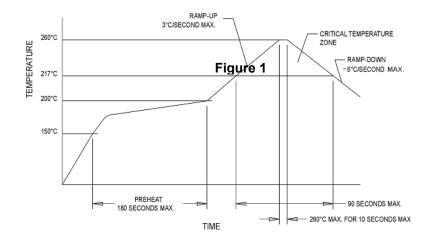




## **Typical Test Circuit & Load Circuit Diagrams:**



## **Soldering Conditions:**



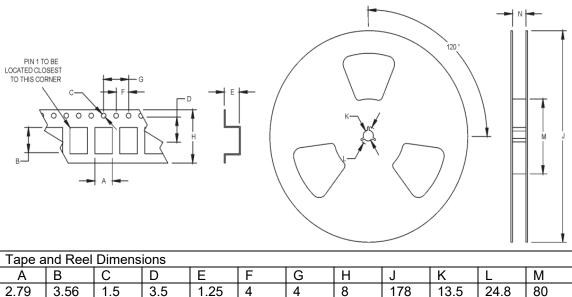
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### **Tape and Reel Specifications:**

All units in mm



### **Datasheet Revision Table:**

Date	Rev.	Author	Details of Revision
08-03-20	А	MM	Original release.